



GL100P08FA9

GL Silicon P-Channel Power MOSFET

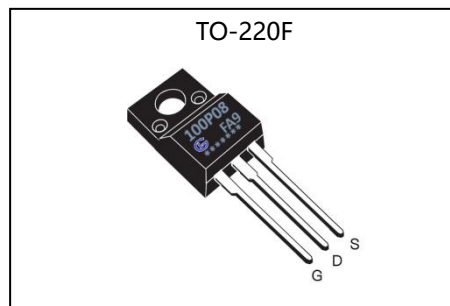
General Description

The GL100P08FA9 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications. The package form is TO-220F, which accords with the RoHS standard.

V_{DSS}	-80	V
I_D	-100	A
P_D	40	W
$R_{DS(ON).TYP}$	7.3	m Ω

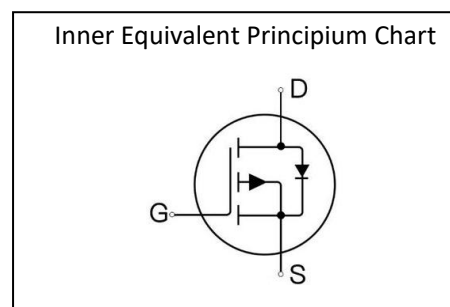
Features

- Fast Switching
- Low Gate Charge and $R_{DS(on)}$
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test



Applications

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



Absolute (Tc=25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-to-Source Voltage	-80	V
I_D	Continuous Drain Current	-100	A
	Continuous Drain Current $T_C=100\text{ }^{\circ}\text{C}$	-70	A
I_{DM}^{a1}	Pulsed Drain Current	-400	A
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}^{a2}	Single Pulse Avalanche Energy	468	mJ
P_D	Power Dissipation	40	W
T_J, T_{stg}	Operating Junction and Storage Temperature Range	150, -55 to 150	$^{\circ}\text{C}$
T_L	Maximum Temperature for Soldering	300	$^{\circ}\text{C}$



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Electrical Characteristics (Tc=25°C unless otherwise specified)

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V _{DSS}	Drain to Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-80	--	--	V
I _{DSS}	Drain to Source Leakage Current	V _{DS} =-80V, V _{GS} =0V, T _a =25°C	--	--	-10	μA
I _{GSS(F)}	Gate to Source Forward Leakage	V _{GS} =+16V	--	--	1	μA
I _{GSS(R)}	Gate to Source Reverse Leakage	V _{GS} =-16V	--	--	-1	μA

ON Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
R _{DS(ON)}	Drain-to-Source On-Resistance	V _{GS} =-10V, I _D =-50A	--	7.3	8.0	mΩ
R _{DS(ON)}	Drain-to-Source On-Resistance	V _{GS} =-4V, I _D =-50A	--	8.9	11	mΩ
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1.2	--	-2.6	V
Pulse width tp≤380μs, δ≤2%						

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g _{fs}	Forward Transconductance	V _{DS} =-10V, I _D =-50A	--	140	--	S
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-20V f=1.0MHz	--	13400	--	pF
C _{oss}	Output Capacitance		--	1000	--	
C _{rss}	Reverse Transfer Capacitance		--	740	--	

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
t _{d(ON)}	Turn-on Delay Time	R _L =-0.96Ω, V _{DD} =-40V V _{GS} =-10V	--	95	--	ns
t _r	Rise Time		--	1000	--	
t _{d(OFF)}	Turn-Off Delay Time		--	800	--	
t _f	Fall Time		--	820	--	
Q _g	Total Gate Charge	I _D =-100A, V _{DD} =-48V V _{GS} =-10V	--	280	--	nC
Q _{gs}	Gate to Source Charge		--	50	--	
Q _{gd}	Gate to Drain ("Miller")Charge		--	55	--	

Source-Drain Diode Characteristics

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I_S	Continuous Source Current (Body Diode)		--	--	-100	A
I_{SM}	Maximum Pulsed Current (Body Diode)		--	--	-200	A
V_{SD}	Diode Forward Voltage	$I_S = -100A, V_{GS} = 0V$	--	--	1.5	V
t_{rr}	Reverse Recovery Time	$I_S = -100A, T_j = 25^\circ C$	--	120	--	ns
Q_{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s, V_{GS} = 0V$	--	380	--	nC

Pulse width $t_p \leq 380\mu s, \delta \leq 2\%$

Symbol	Parameter	Typ.	Units
$R_{\theta JA}$	Junction-to-Ambient	3.125	$^\circ C/W$

^{a1}: Repetitive rating; pulse width limited by maximum junction temperature

^{a2}: $V_{DD} = -48V, L = 100\mu H, I_{AV} = -60A$

Test Circuits

Fig.1 Unclamped Inductive Switching Test Circuit

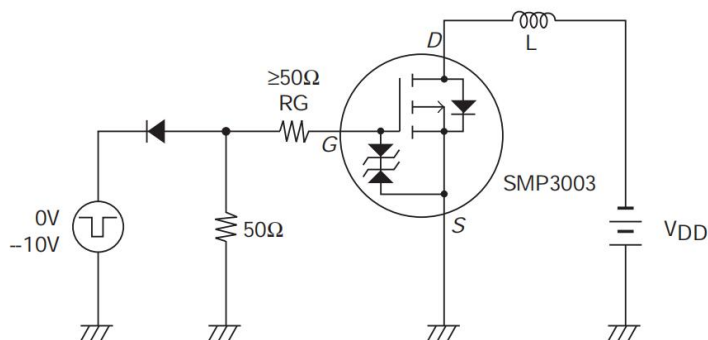


Fig.2 Switching Time Test Circuit

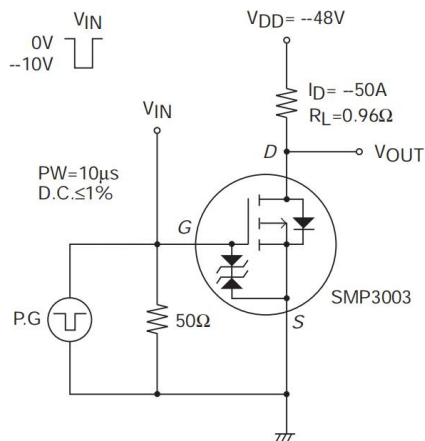
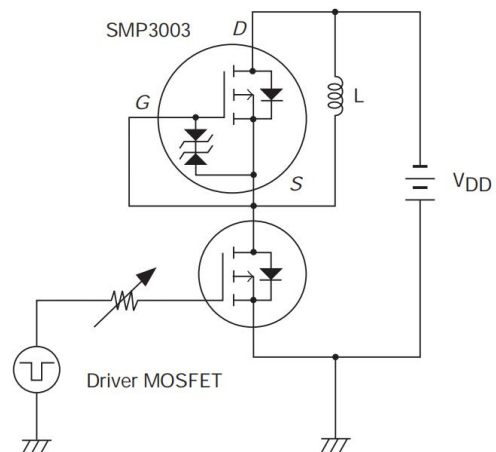


Fig.3 Reverse Recovery Time Test Circuit



Characteristics Curves

